

PRODUCT / PROCESS CHANGE NOTIFICATION (PCN)

PCN Number:	CC164601																					
Notification Subject:	CRB 16-0897 Final Notice: Qualification of ATP assembly site for AT97SC3204 device family available in 40L MLF (or VQFN) package.																					
PCN Issue Date:	January 10, 2017																					
Change Category:	Manufacturing location																					
PCN Status:	Final notification																					
Microchip/Atmel Parts Affected:	Please open the attachments included with this PCN labeled as PCN_#_Affected_CPN. Note: for your convenience Microchip/Atmel includes identical files in two formats (.pdf and .xls)																					
Description of Change:	Qualification of ATP assembly site for AT97SC3204 device family available in 40L MLF (or VQFN) package.																					
Pre Change:	ATK assembly site																					
Post Change:	ATP assembly site																					
Pre and Post Change Summary:	<table border="1"><thead><tr><th>Description</th><th>Pre Change</th><th>Post Change</th></tr></thead><tbody><tr><td>Assembly site</td><td>ATK assembly site</td><td>ATP assembly site</td></tr><tr><td>Wire material</td><td>Au wire</td><td>Au wire</td></tr><tr><td>Wire diameter</td><td>1.0 mil</td><td>0.8 mil</td></tr><tr><td>Die attach material</td><td>8290</td><td>8290</td></tr><tr><td>Molding compound material</td><td>G700</td><td>G700</td></tr><tr><td>Lead frame material</td><td>C194</td><td>C194</td></tr></tbody></table>	Description	Pre Change	Post Change	Assembly site	ATK assembly site	ATP assembly site	Wire material	Au wire	Au wire	Wire diameter	1.0 mil	0.8 mil	Die attach material	8290	8290	Molding compound material	G700	G700	Lead frame material	C194	C194
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Die attach material	8290	8290																				
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Impacts to Data Sheet:	None																					
Change Impact:	None																					
Reason for Change:	To improve manufacturability by qualifying ATP assembly site. ATK assembly site will be shutting down its current line and will no longer have manufacturing support to assemble AT97SC3204 device family available in 40L MLF (or VQFN) package.																					

Change Implementation Status: In Progress

Estimated First Ship Date: April 3, 2017

Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

Workweek	January 2017				→	April 2017				
	01	02	03	04		13	14	15	16	17
Qual Report Availability		X								
Final PCN Issue Date		X								
Estimated Implementation Date							X			

Method to Identify Change: COO (Country of Origin) code on the marking

Qualification Report : Please open the attachments included with this PCN labeled as PCN_#_Qual Report

Data Sheet: To view the applicable data sheet please go to the [document library](#) found on [atmel.com](#)

Revision History: January 10, 2017: Issued final notification.

Please contact your local [Microchip](#) or [Atmel](#) Sales Office or Distributor with questions or concerns regarding this notification.